

MC74LCX08

Low-Voltage CMOS Quad 2-Input AND Gate

With 5 V-Tolerant Inputs

The MC74LCX08 is a high performance, quad 2-input AND gate operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX08 inputs to be safely driven from 5.0 V devices.

Current drive capability is 24 mA at the outputs.

Features

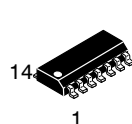
- Designed for 2.3 V to 3.6 V V_{CC} Operation
- 5.0 V Tolerant Inputs – Interface Capability With 5.0 V TTL Logic
- LVTTTL Compatible
- LVC MOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μ A) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V
Machine Model >200 V
- These Devices are Pb-Free and are RoHS Compliant



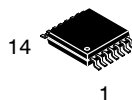
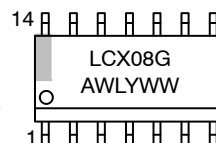
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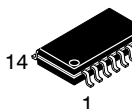
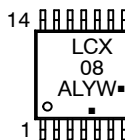
MARKING DIAGRAMS



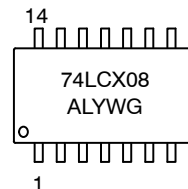
SOIC-14
D SUFFIX
CASE 751A



TSSOP-14
DT SUFFIX
CASE 948G



SOEIAJ-14
M SUFFIX
CASE 965



A = Assembly Location
L, WL = Wafer Lot
Y = Year
W, WW = Work Week
G or ■ = Pb-Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MC74LCX08

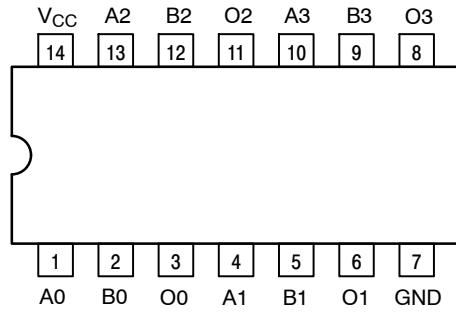


Figure 1. Pinout: 14-Lead (Top View)

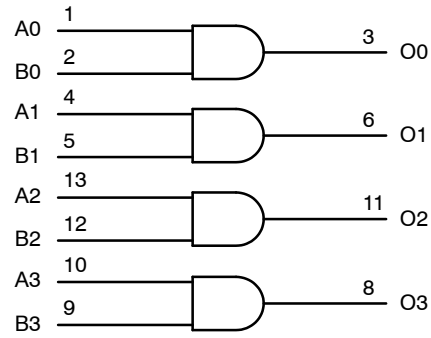


Figure 2. Logic Diagram

PIN NAMES

Pins	Function
An, Bn	Data Inputs
On	Outputs

TRUTH TABLE

Inputs		Outputs
An	Bn	On
L	L	L
L	H	L
H	L	L
H	H	H

H = High Voltage Level

L = Low Voltage Level

For I_{CC} reasons, DO NOT FLOAT Inputs

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
V _I	DC Input Voltage	-0.5 ≤ V _I ≤ +7.0		V
V _O	DC Output Voltage	-0.5 ≤ V _O ≤ V _{CC} + 0.5	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

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RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Type	Max	Unit
V_{CC}	Supply Voltage Operating Data Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
V_I	Input Voltage	0		5.5	V
V_O	Output Voltage (HIGH or LOW State) (3-State)	0		V_{CC}	V
I_{OH}	HIGH Level Output Current $V_{CC} = 3.0\text{ V} - 3.6\text{ V}$ $V_{CC} = 2.7\text{ V} - 3.0\text{ V}$ $V_{CC} = 2.3\text{ V} - 2.7\text{ V}$			-24 -12 -8	mA
I_{OL}	LOW Level Output Current $V_{CC} = 3.0\text{ V} - 3.6\text{ V}$ $V_{CC} = 2.7\text{ V} - 3.0\text{ V}$ $V_{CC} = 2.3\text{ V} - 2.7\text{ V}$			+24 +12 +8	mA
T_A	Operating Free-Air Temperature	-40		+85	°C
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate, V_{IN} from 0.8 V to 2.0 V, $V_{CC} = 3.0\text{ V}$	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = -40^\circ\text{C to } +85^\circ\text{C}$		Unit
			Min	Max	
V_{IH}	HIGH Level Input Voltage (Note 2)	$2.3\text{ V} \leq V_{CC} \leq 2.7\text{ V}$	1.7		V
		$2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}$	2.0		
V_{IL}	LOW Level Input Voltage (Note 2)	$2.3\text{ V} \leq V_{CC} \leq 2.7\text{ V}$		0.7	V
		$2.7\text{ V} \leq V_{CC} \leq 3.6\text{ V}$		0.8	
V_{OH}	HIGH Level Output Voltage	$2.3\text{ V} \leq V_{CC} \leq 3.6\text{ V}$; $I_{OH} = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$		V
		$V_{CC} = 2.3\text{ V}$; $I_{OH} = -8\text{ mA}$	1.8		
		$V_{CC} = 2.7\text{ V}$; $I_{OH} = -12\text{ mA}$	2.2		
		$V_{CC} = 3.0\text{ V}$; $I_{OH} = -18\text{ mA}$	2.4		
		$V_{CC} = 3.0\text{ V}$; $I_{OH} = -24\text{ mA}$	2.2		
V_{OL}	LOW Level Output Voltage	$2.3\text{ V} \leq V_{CC} \leq 3.6\text{ V}$; $I_{OL} = 100\text{ }\mu\text{A}$		0.2	V
		$V_{CC} = 2.3\text{ V}$; $I_{OL} = 8\text{ mA}$		0.6	
		$V_{CC} = 2.7\text{ V}$; $I_{OL} = 12\text{ mA}$		0.4	
		$V_{CC} = 3.0\text{ V}$; $I_{OL} = 16\text{ mA}$		0.4	
		$V_{CC} = 3.0\text{ V}$; $I_{OL} = 24\text{ mA}$		0.55	
I_I	Input Leakage Current	$2.3\text{ V} \leq V_{CC} \leq 3.6\text{ V}$; $0\text{ V} \leq V_I \leq 5.5\text{ V}$		± 5	μA
I_{CC}	Quiescent Supply Current	$2.3 \leq V_{CC} \leq 3.6\text{ V}$; $V_I = \text{GND or } V_{CC}$		10	μA
		$2.3 \leq V_{CC} \leq 3.6\text{ V}$; $3.6 \leq V_I \text{ or } V_O \leq 5.5\text{ V}$		± 10	
ΔI_{CC}	Increase in I_{CC} per Input	$2.3 \leq V_{CC} \leq 3.6\text{ V}$; $V_{IH} = V_{CC} - 0.6\text{ V}$		500	μA

2. These values of V_I are used to test DC electrical characteristics only.

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AC CHARACTERISTICS $t_R = t_F = 2.5 \text{ ns}$; $R_L = 500 \Omega$

Symbol	Parameter	Waveform	Limits						Unit
			T _A = −40°C to +85°C						
			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 2.5 V ± 0.2 V		
			C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
			Min	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay Time	1	1.5	5.5	1.5	6.2	1.5	6.6	ns
t _{PHL}	Input to Output		1.5	5.5	1.5	6.2	1.5	6.6	
t _{OSHL}	Output-to-Output Skew			1.0					ns
t _{OSLH}	(Note 3)			1.0					

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

DYNAMIC SWITCHING CHARACTERISTICS

Symbol	Characteristic	Condition	$T_A = +25^\circ\text{C}$			Unit
			Min	Typ	Max	
V_{OLP}	Dynamic LOW Peak Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $V_{IH} = 3.3 \text{ V}$, $V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}$, $C_L = 30 \text{ pF}$, $V_{IH} = 2.5 \text{ V}$, $V_{IL} = 0 \text{ V}$		0.8 0.6		V V
V_{OLV}	Dynamic LOW Valley Voltage (Note 4)	$V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $V_{IH} = 3.3 \text{ V}$, $V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}$, $C_L = 30 \text{ pF}$, $V_{IH} = 2.5 \text{ V}$, $V_{IL} = 0 \text{ V}$		-0.8 -0.6		V V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	$V_{CC} = 3.3 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC}	7	pF
C_{OUT}	Output Capacitance	$V_{CC} = 3.3 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC}	8	pF
C_{PD}	Power Dissipation Capacitance	10 MHz, $V_{CC} = 3.3 \text{ V}$, $V_I = 0 \text{ V}$ or V_{CC}	25	pF

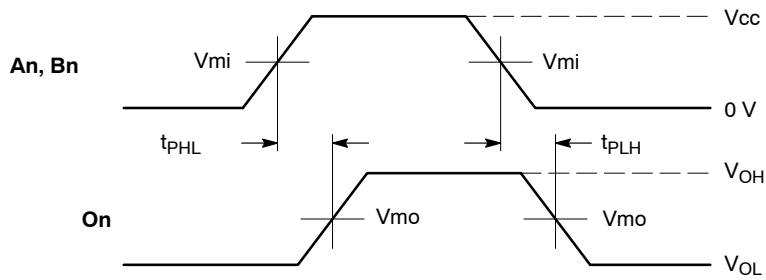
ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX08DG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74LCX08DR2G	SOIC-14 (Pb-Free)	2500 Tape & Reel
MC74LCX08DTG	TSSOP-14*	96 Units / Rail
MC74LCX08DTR2G	TSSOP-14*	2500 Tape & Reel
MC74LCX08MELG	SOEIAJ-14 (Pb-Free)	2000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

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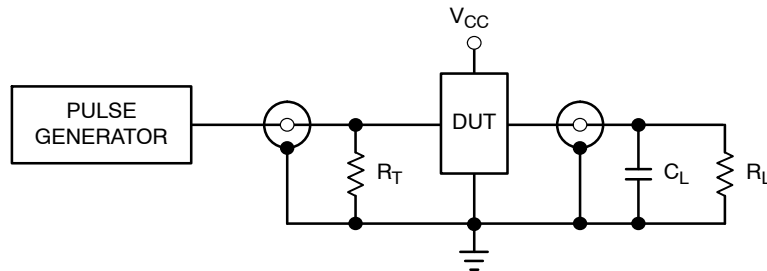


WAVEFORM 1 - PROPAGATION DELAYS

$t_R = t_F = 2.5 \text{ ns}$, 10% to 90%; $f = 1 \text{ MHz}$; $t_W = 500 \text{ ns}$

Symbol	Vcc		
	3.3 V \pm 0.3 V	2.7 V	2.5 V \pm 0.2 V
Vmi	1.5 V	1.5 V	Vcc/2
Vmo	1.5 V	1.5 V	Vcc/2

Figure 3. AC Waveforms



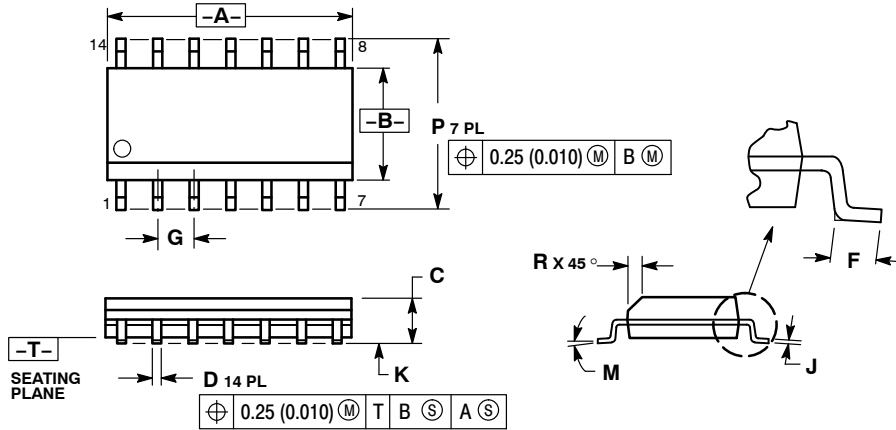
$C_L = 50 \text{ pF}$ at $V_{CC} = 3.3 \pm 0.3 \text{ V}$ or equivalent (includes jig and probe capacitance)
 $C_L = 30 \text{ pF}$ at $V_{CC} = 2.5 \pm 0.2 \text{ V}$ or equivalent (includes jig and probe capacitance)
 $R_L = R_1 = 500 \Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 4. Test Circuit

MC74LCX08

PACKAGE DIMENSIONS

SOIC-14
CASE 751A-03
ISSUE J

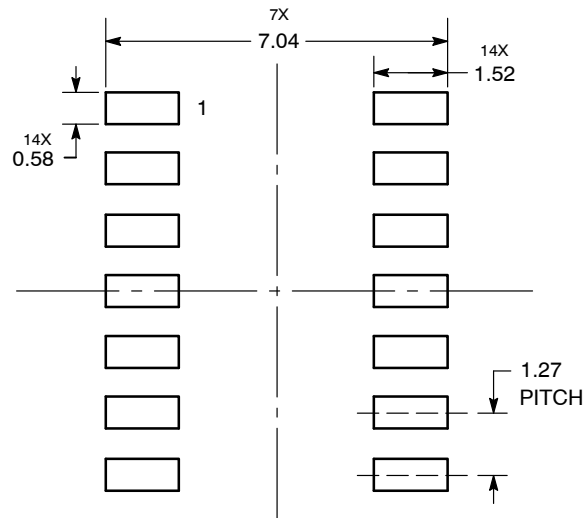


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	8.55	8.75	0.337	0.344
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
E	0.40	1.25	0.016	0.049
F	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

SOLDERING FOOTPRINT*



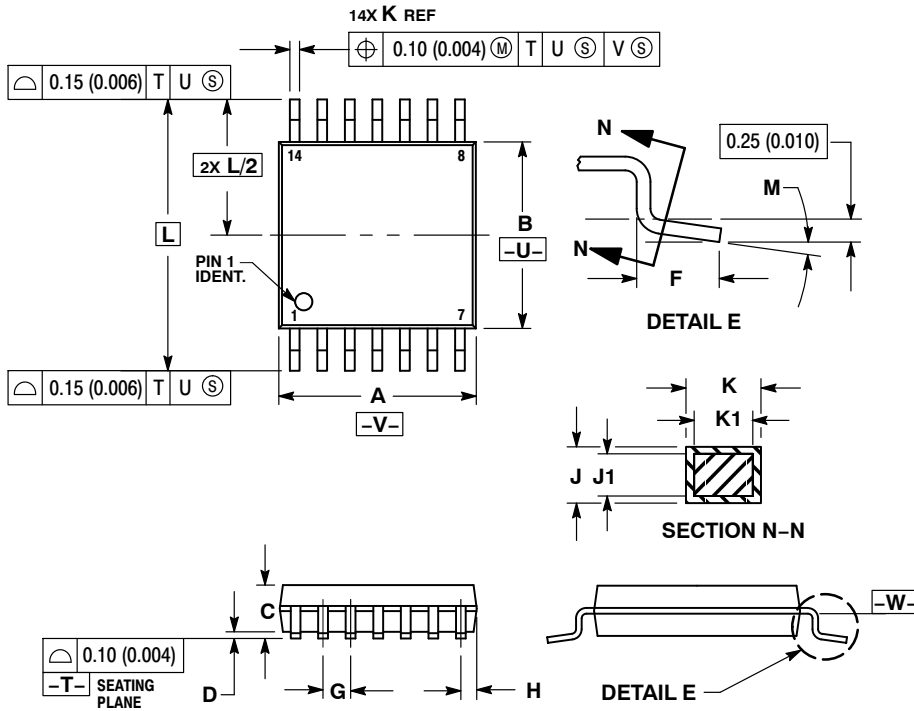
DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

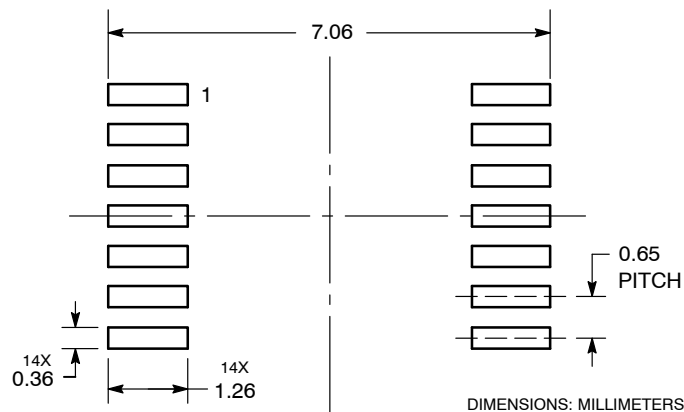
TSSOP-14
CASE 948G-01
ISSUE B



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
H	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	BSC	0.252	BSC
M	0°	8°	0°	8°

SOLDERING FOOTPRINT*

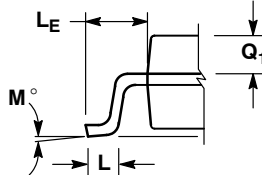
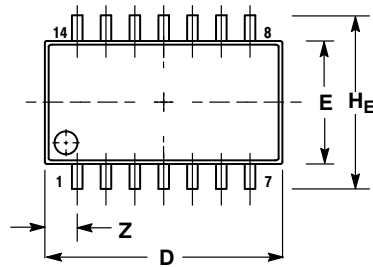


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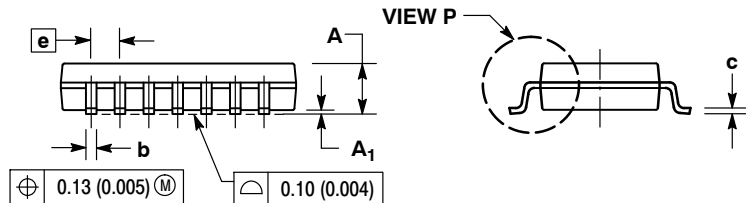
MC74LCX08

PACKAGE DIMENSIONS

SOEIAJ-14
CASE 965-01
ISSUE B




DETAIL P



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q ₁	0.70	0.90	0.028	0.035
Z	---	1.42	---	0.056

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